

REMARKS

The present application contains claims 1-315, the status of which is as follows:

(a) Claims 1-276 have been canceled.

(b) Claims 277-315 are new.

No new matter has been added. Reconsideration is respectfully requested.

Claim 1 was rejected under 35 U.S.C. 101 as claiming the same invention as that of claim 1 of prior US Patent 6,712,772. Claim 1 was additionally objected to because of an informality in the claim. The Applicant has canceled claim 1, rendering the rejection and objection moot.

Claims 277-315 are new. These claims find support in the application as filed on p. 7, line 27 – p. 9, line 4; p. 15, line 22 – p. 16, line 24; p. 25, line 10 – p. 27, line 20; and Fig. 3A. For example, the claims find support as shown in the following table:

Claims	Support in specification as filed
277, 278, 302, and 303	<p>There is yet additionally provided, in accordance with a preferred embodiment of the present invention, apparatus which is adapted to be placed in a patient, including:</p> <p style="padding-left: 40px;">circuitry, which is adapted to be placed in a patient;</p> <p style="padding-left: 40px;">a lead wire; and</p> <p style="padding-left: 40px;">an electrically-conductive connector, which is crimped to the lead wire so as to be electrically coupled thereto, and which is soldered to the circuitry (p. 15, lines 22-31).</p> <p>In some preferred embodiments, a stainless steel cylinder is mechanically coupled to an MP35N wire, for example by crimping (p. 8, 25-27).</p>
279 and 304	<p>In a preferred embodiment, the connector includes a hollow tube, wherein a portion of the lead wire is disposed within the hollow tube, and wherein the hollow tube is crimped to the portion of the lead wire (p. 16, lines 4-7).</p>
280-282 and	<p>Typically, the lead wire includes an MP35N lead wire, a</p>

305-307	platinum/iridium lead wire, or a wire including 1-60% iron by weight (p. 16, lines 1-3).
283-284 and 308-309	The following solution, and that elaborated more completely in the Detailed Description of Preferred Embodiments, while described with respect to MP35N by way of illustration, applies as well to platinum/iridium and other alloys having low iron content (e.g., 1-60% iron, 1-40% iron, or 1-20% iron) (p. 8, lines 7-12).
285 and 310	To obtain improved electrical conduction, cylinders 130 are preferably coated with gold prior to soldering (p. 26, lines 16-18).
286 and 311	Alternatively, cylinders 130 are treated with phosphoric acid to improve electrical conduction (p. 26, lines 18-20).
287-288 and 312-313	For some applications, the circuitry is adapted to be implanted in the patient. For other applications, the circuitry is adapted to be incorporated in a catheter (p. 16, lines 10-12).
289 and 314	For example, the techniques described herein may be applied to a lead wire having MP35N over a silver core (p. 8, lines 16-18).
290 and 315	Typically, but not necessarily, the connector includes stainless steel (p. 16, lines 8-9).
291-296	In a preferred embodiment, the circuitry includes a sensor, such as a pressure sensor, a temperature sensor, and/or a chemical sensor. Alternatively or additionally, the sensor includes an electrode, adapted to sense electrical activity in tissue of the patient where the apparatus is placed. Further alternatively or additionally, the sensor includes a flow sensor, adapted to sense a flow of blood in a vicinity of the apparatus (p. 16, lines 13-20).
297-301	For some applications, the circuitry includes an active element, such as a stimulating electrode, a light source adapted to facilitate photodynamic therapy, an electroactive polymer, and/or a mechanical actuator (p. 16, lines 21-24).

The Applicant believes the amendments and remarks presented hereinabove to be fully responsive to all of the grounds of rejection and objection raised by the Examiner.

Notice of allowance of the present application is respectfully requested.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Julian H. Cohen', is written over a horizontal line.

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